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MiNaPAD Forum 2023

10th Micro/Nano-Electronics
Packaging and Assembly,
Design and Manufacturing Forum

WTC
GRENOBLE
France

June 7th - 8th

EXHIBITION & CONFERENCES

WORLD TRADE CENTER
CHAMBRE DE COMMERCE & D'INDUSTRIE DE GRENOBLE



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Organized by

IMAPS - International Microelectronics Assembly and Packaging Society

17 rue de l'Amiral Hamelin - 75016 Paris - France

Mob: +33 (0) 7 88 75 59 86

imaps.france@orange.fr - www.france.imapseurope.org

Wednesday June 7th

8h45 Welcome to MiNaPAD

9h00 Opening by Jean-Marc YANNOU (Auditorium)

9h30 Keynote: Laurent HERARD (STMicroelectronics – BEMT R&D Manager)
Packaging innovation – A key enabler for future mobility

10h15 – 10h40 Exhibition Opening (Exhibition Hall) / Coffee break sponsored by



SESSION A: Wafer Level Packaging & Flip Chip (Auditorium)

10h45 Advanced vertical interconnections for fan-out wafer level packaging applications
(Aurelia Plihon / CEA-Leti - France)

11h15 Advanced Package Platform VIPACK : FOSiP
(Chin-Cheng Kuo / ASE group - Taiwan)

11h45 Packaging of a 25 flip chips module on large dimension AlN ceramic substrate keeping low dead areas and tight planarity
(Sarah Renault / CEA-Leti – France)

12h15 Fabrication and characterization of a 2 layers face-to-back test vehicle with high density TSV
(Jerzy-Javier Suarez-Berru / CEA-Leti - France)

SESSION B: Characterization & Reliability (Mont Blanc)

Comparative study on electrical performance of wire-bonded BGA packages using non-plating line vs etch-back technology

(Damian Halicki / STMicroelectronics - Italy)

Comparative study of thermal fatigue life of polymer core solder balls (PCSB) and SAC solder balls in BGA interconnections

(I. Malkorra / ESME - France)

Thermal characteristic study of epoxy molding compound with different filler composition

(Bo Yu Huang / ASE group - Taiwan)

Finite elements analysis of solder joints during thermal shock tests correlation with dye penetration

(Khalil Maarouf / VALEO - France)

12h45 – 13h35 Lunch (Exhibition Hall) sponsored by



SESSION C: Interconnections (Auditorium)

13h40 The study of pure Cu and Pd coated Cu wire-bonding on nano-twinned Cu pad/finger
(Erh-Ju Lin / ASE group - Taiwan)

14h10 Cu second bond response on thin silver pre-plated leadframe packages
(Mirko Alesi / STMicroelectronics - Italy)

14h40 Next generation lead-free solder paste for advanced packages
(B. Senthil Kumar / HERAEUS - Germany)

15h10 Multiphase full wave system
(Jean-Christophe Riou / SAFRAN - France)

SESSION D: MEMs & Optical Packages (Mont Blanc)

Test on package: design and manufacturing of package aimed to electromechanical characterization of MEMS structures

(Marco Del Sarto / STMicroelectronics – Italy)

3D silicon photonic interposer process integration for chiplet based 3D systems

(Damien Saint-Patrice / CEA-Leti - France)

Wafer level optical package for ambient light sensor for mobile and wearable applications with integrated multi-lens array

(Niek van Haare / BESI - Netherlands)

3D heterogeneous integration of meta surface lens in an optical package

(Patrick Laurent / STMicroelectronics - France)

15h40 – 16h00 Exhibition / Coffee break sponsored by  life.augmented

**SESSION E: Panel Session
(Auditorium)**

16h05 Writing Invention Disclosures to Optimize Patent Value in Europe and the U.S
(Richard P. Gilly / Archer & Greiner P.C. - USA)

16h30 Advanced packaging technology & market trends
(Bilal Hachemi / YOLE Developments - France)

16h55 **Round Table: The Reindustrialization of Semiconductor Packaging in Europe in the context of the EU Chips Act**

Moderator: BOULAY Sanae (NXP) and De LANGLADE Renaud (EPOSS)

Speakers: IBRAHIM Mario (AT&S), OBERNDORFF Pascal (NXP), HERARD Laurent (STMicroelectronics), YANNOU Jean-Marc (ASE Europe), David HIEN (EGIDE)

18h00

18h30 **Social Event : Château de la Commanderie**

Sponsored by



18h30-19h00: Transportation by FAURE Bus from WTC conference

19h00-20h00: Appetizers & Music by Alpes concerts

20h00: Dinner

22h30: Return to WTC conference by FAURE Bus



Overview Château de la Commanderie (38320 EYBENS)



Thursday June 8th

8h30 - Opening exhibition and conferences

Session F: Encapsulation (Auditorium)

- 08h45** The phenomenon of creep and overflow in gel dispense process
(Shih Kun Lo / ASE group - Taiwan)
- 09h15** Enabling semiconductor packaging materials for advanced flip-chip and heterogeneous integration
(Ruud de Wit / HENKEL - Netherland)

Session G: BGA manufacturing (Mont Blanc)

- Advanced IC substrates - challenges in manufacturing and supply chain
(Daniel Schulze / DYCONEX - Switzerland)
- Fabrication and characterization of soft polymer core solder balls (PCSB) for BGA interconnections
(I. Malkorra / ESME - France)

9h50 Keynote: Pascal OBERNDORFF (NXP – Head of Package Core Technology)
Title

10h30 – 10h50 Exhibition & Coffee break (Exhibition Hall) sponsored by



Session H: Manufacturing - Plasma (Auditorium)

- 10h55** Panasonic plasma cleaning technology and predictive maintenance by using plasma monitor function
(James Weber / PANASONIC - Germany)
- 11h25** Cleaning of silicone and hydrocarbon contact residue using atmospheric plasma
(Daniel Pascual / ONTOS Equipment Systems – USA)
- 11h55** Improving CCP chamber-plasma-cleaning performance using plasma light emission (OES) analysis data
(Jong Won Oh / VISION Semicon – Republic of Korea)

Session I: Manufacturing - Equipment's (Mont Blanc)

- Advanced laser grooving and dicing to enable high quality separation of next generation thin semiconductor devices
(Gerald Klug / DISCO – Germany)
- Direct writing technologies for interconnection in electronic packaging
(Elodie Pereira / CTTC - France)
- An innovative contactless technology for high resolution, high speed, conductive & dielectric materials deposition
(Stéphane Etienne / I-O-TECH, Israel)

12h25 – 13h30 Lunch & Exhibition (Exhibition Hall) sponsored by



Session J: Advanced Interconnections (Auditorium)

- 13h35** Development of stretchable and removable electrical interconnection solution for ultra-thin electronic components
(Auriane Despax-Ferreres / CEA-LITEN - France)
- 14h05** High density interconnect above active CMOS structures utilizing optimized klettswelding of nanowires
(Andreas Kramer / TU Darmstadt - Germany)
- 14h35** The failure mechanism of μ -CuP employed in sensor packages
(Erh-Juh Lin / ASE group - Taiwan)
- 15h05** Hybrid in-mold electronics process towards novel 3d packaging of components and systems
(Philippe Lombard / University of Lyon - France)

15h35 Closing by Jean-Marc YANNOU (Auditorium)

15h40 -16h00 Exhibition /Coffee Break 
16h00 End of MiNaPAD 2023 conference

List of Exhibitors

28/04/2023

Booth number	Company
1	ASE
2	ELECTRON-MEC
3	
4	DAVUM - Option
5	
6	INTRASPEC - Option
7	PROTAVIC
8	MST
9	ELEMCA
10	METRONELEC
11	CTS - Option
12	SET
13	KYOCERA
14	NITERRA / NTK
15	ACCELONIX
16	AEMTEC
17	EGIDE
18	DISCO
19	TAIPRO
20	ISP SYSTEM
21	BT ELECTRONICS POLY DISPENSING SYSTEMS
22	TELEDYNE E2V
23	HYBRID
24	MICROTEST ONTOS
25	NANOTEC
26	SERMA Microelectronics
27	MICRONOR
28	CEA
29	FINETECH
30	JCET Group Co., Ltd



REGISTRATION FORM

Mrs, M.

Name:Firstname:

Company:

Job Title:

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Individual registration:

By email: imaps.france@orange.fr

By Post: IMAPS, 17 rue de l'Amiral Hamelin, 75016 Paris

By Internet: <https://event.imaps.france.org>

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Students and Teachers (University and Laboratories), retiree: **0 Euro** conferences attendance, proceedings, without social event – Registration is mandatory with justification.



Speakers:

180 € VAT excl.

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Chairs, Technical Committee:

320 € VAT excl.

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IMAPS Member IMAPS 2023 and IEEE 2023 Membership

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Purchase order (PO)

IMAPS BANK REFERENCES

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